

Features

- Advanced Trench MOS Technology
- Low Gate Charge
- 100% EAS Guaranteed
- Green Device Available

Product Summary

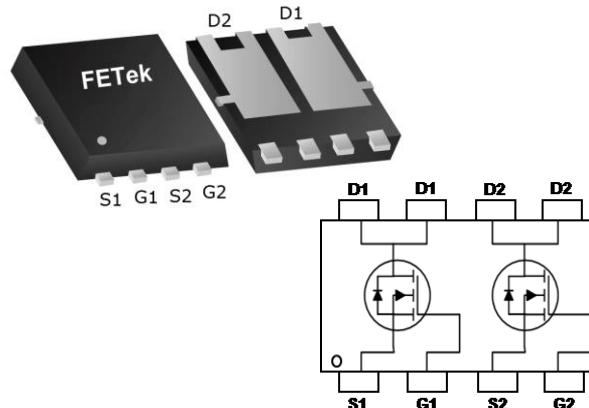


| BVDSS | RDS(ON) | ID |
|-------|---------|-----|
| 60V | 15mΩ | 29A |

Application

- Motor Control.
- DC/DC Converter.
- Synchronous rectifier applications.

PRPAK3x3 Pin Configuration



Absolute Maximum Ratings

| Symbol | Parameter | Rating | Units |
|---------------------------------------|--|------------|-------|
| V _{DS} | Drain-Source Voltage | 60 | V |
| V _{GS} | Gate-Source Voltage | ±20 | V |
| I _D @T _C =25°C | Continuous Drain Current, V _{GS} @ 10V ¹ | 29 | A |
| I _D @T _C =100°C | Continuous Drain Current, V _{GS} @ 10V ¹ | 23 | A |
| I _{DM} | Pulsed Drain Current ² | 58 | A |
| EAS | Single Pulse Avalanche Energy ³ | 45 | mJ |
| I _{AS} | Avalanche Current | 30 | A |
| P _D @T _C =25°C | Total Power Dissipation ⁴ | 20.8 | W |
| T _{STG} | Storage Temperature Range | -55 to 150 | °C |
| T _J | Operating Junction Temperature Range | -55 to 150 | °C |

Thermal Data

| Symbol | Parameter | Typ. | Max. | Unit |
|------------------|--|------|------|------|
| R _{θJA} | Thermal Resistance Junction-ambient ¹ | --- | 62.5 | °C/W |
| R _{θJC} | Thermal Resistance Junction-case ¹ | --- | 6 | °C/W |

Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)

| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Unit |
|--------------------------|--|---|------|------|-----------|------------------|
| BV_{DSS} | Drain-Source Breakdown Voltage | $V_{\text{GS}}=0\text{V}$, $I_D=250\mu\text{A}$ | 60 | --- | --- | V |
| $R_{\text{DS(ON)}}$ | Static Drain-Source On-Resistance ² | $V_{\text{GS}}=10\text{V}$, $I_D=10\text{A}$ | --- | 10.5 | 15 | $\text{m}\Omega$ |
| | | $V_{\text{GS}}=4.5\text{V}$, $I_D=10\text{A}$ | --- | 15.7 | 21 | $\text{m}\Omega$ |
| $V_{\text{GS(th)}}$ | Gate Threshold Voltage | $V_{\text{GS}}=V_{\text{DS}}$, $I_D=250\mu\text{A}$ | 1.2 | 2 | 2.3 | V |
| I_{DSS} | Drain-Source Leakage Current | $V_{\text{DS}}=48\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=25^\circ\text{C}$ | --- | --- | 1 | uA |
| | | $V_{\text{DS}}=48\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=55^\circ\text{C}$ | --- | --- | 5 | |
| I_{GSS} | Gate-Source Leakage Current | $V_{\text{GS}}=\pm 20\text{V}$, $V_{\text{DS}}=0\text{V}$ | --- | --- | ± 100 | nA |
| R_g | Gate Resistance | $V_{\text{DS}}=0\text{V}$, $V_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$ | --- | 1.0 | --- | Ω |
| Q_g | Total Gate Charge (10V) | $V_{\text{DS}}=30\text{V}$, $V_{\text{GS}}=10\text{V}$, $I_D=10\text{A}$ | --- | 15.8 | --- | nC |
| Q_g | Total Gate Charge (4.5V) | | --- | 8.7 | --- | |
| Q_{gs} | Gate-Source Charge | | --- | 3.1 | --- | |
| Q_{gd} | Gate-Drain Charge | | --- | 4.4 | --- | |
| $T_{\text{d(on)}}$ | Turn-On Delay Time | $V_{\text{DD}}=30\text{V}$, $V_{\text{GS}}=10\text{V}$, $R_G=3.3\Omega$, $I_D=10\text{A}$ | --- | 5.8 | --- | ns |
| T_r | Rise Time | | --- | 3.5 | --- | |
| $T_{\text{d(off)}}$ | Turn-Off Delay Time | | --- | 26 | --- | |
| T_f | Fall Time | | --- | 3.2 | --- | |
| C_{iss} | Input Capacitance | $V_{\text{DS}}=30\text{V}$, $V_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$ | --- | 760 | --- | pF |
| C_{oss} | Output Capacitance | | --- | 272 | --- | |
| C_{rss} | Reverse Transfer Capacitance | | --- | 26 | --- | |

Diode Characteristics

| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Unit |
|-----------------|--|--|------|------|------|------|
| I_s | Continuous Source Current ^{1,5,6} | $V_G=V_D=0\text{V}$, Force Current | --- | --- | 29 | A |
| V_{SD} | Diode Forward Voltage ² | $V_{\text{GS}}=0\text{V}$, $I_s=1\text{A}$, $T_J=25^\circ\text{C}$ | --- | --- | 1.2 | V |

Note :

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
2. Single pulse width limited by junction temperature $T_{J(\text{MAX})}=150^\circ\text{C}$.
- 3.The EAS data shows Max. rating . The test condition is $V_{\text{DD}}=25\text{V}$, $V_{\text{GS}}=10\text{V}$, $L=0.1\text{mH}$, $I_{\text{AS}}=30\text{A}$
- 4.The power dissipation is limited by 150°C junction temperature
- 5.The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

Typical Characteristics

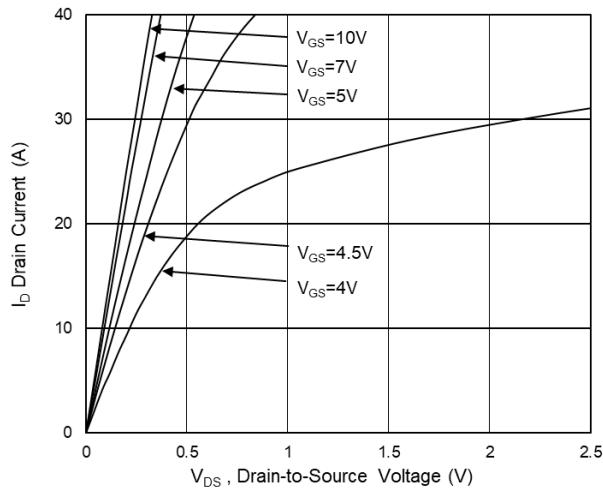


Fig.1 Typical Output Characteristics

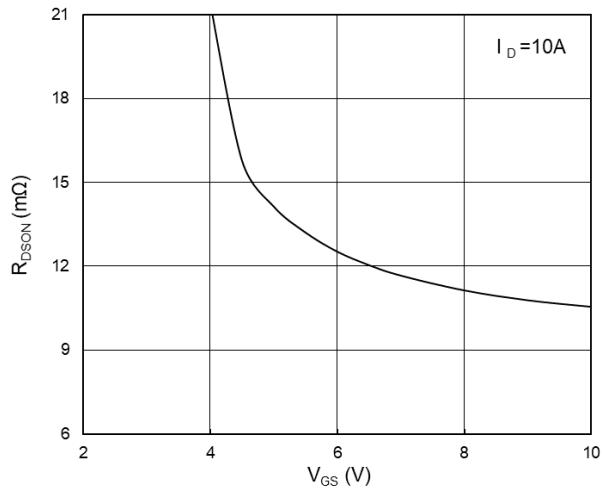


Fig.2 On-Resistance vs G-S Voltage

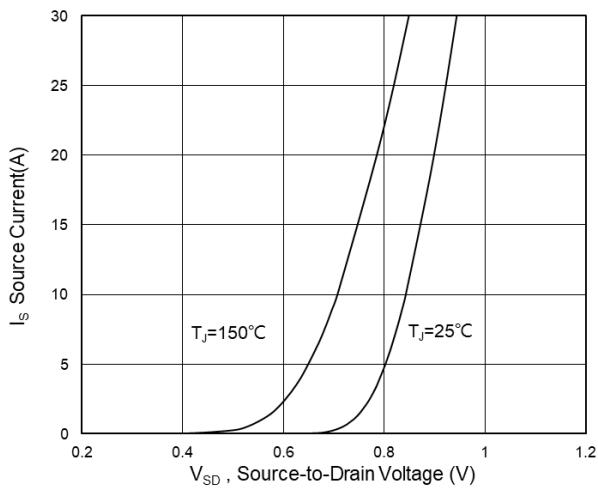


Fig.3 Source Drain Forward Characteristics

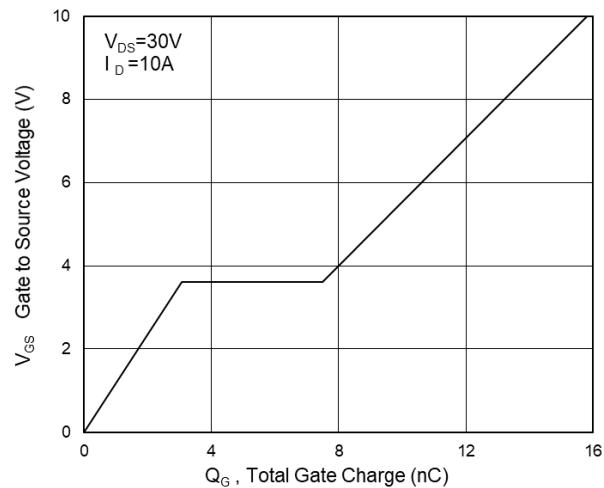


Fig.4 Gate-Charge Characteristics

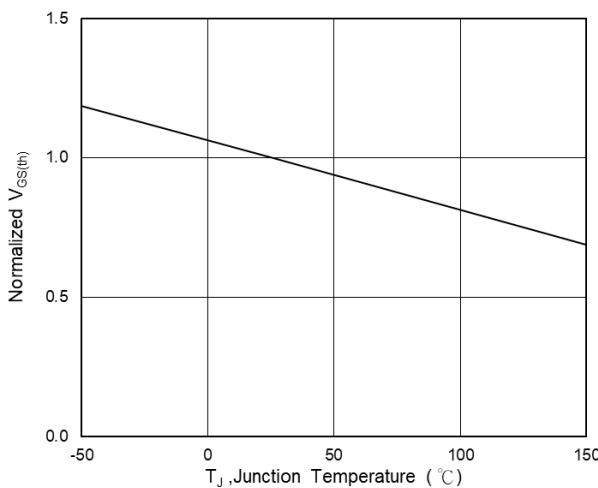


Fig.5 Normalized $V_{GS(th)}$ vs T_J

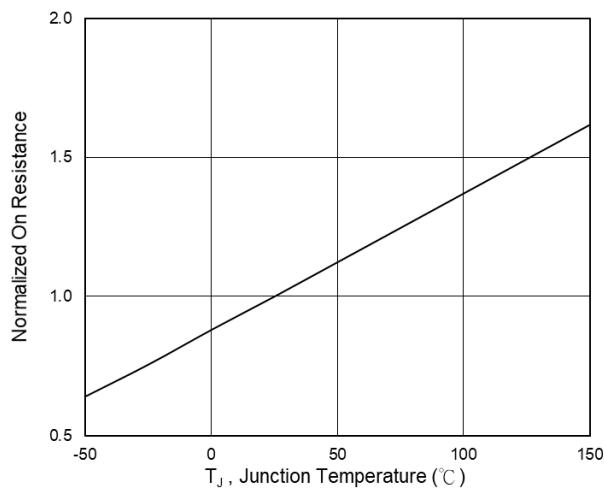
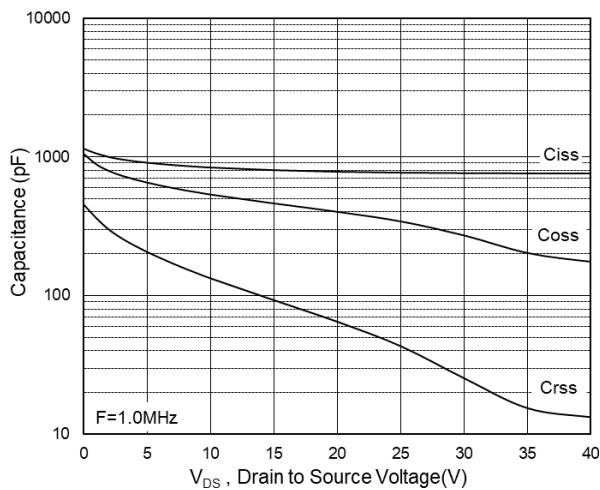
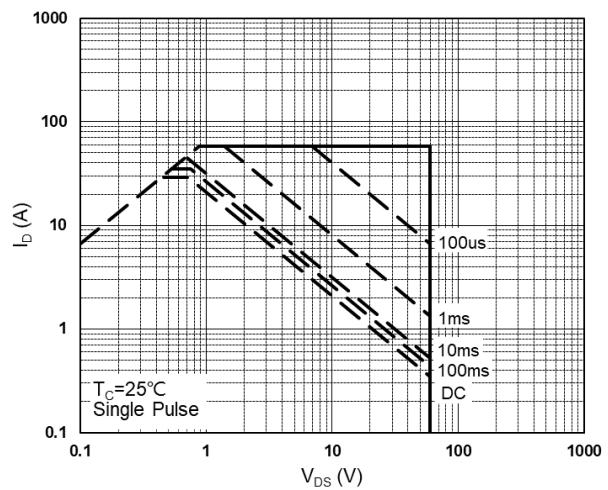
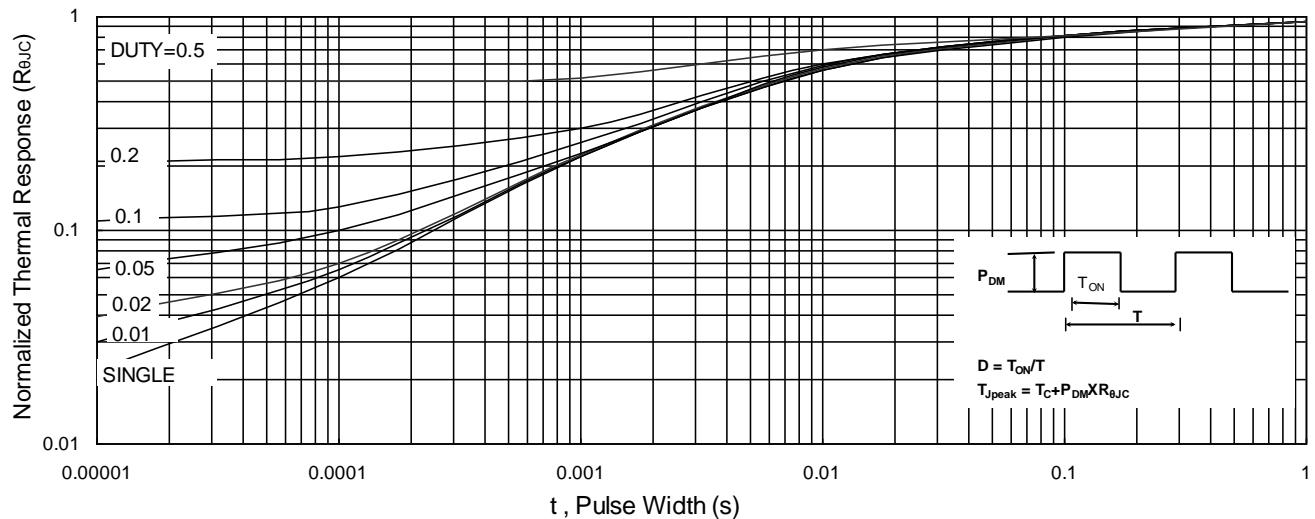
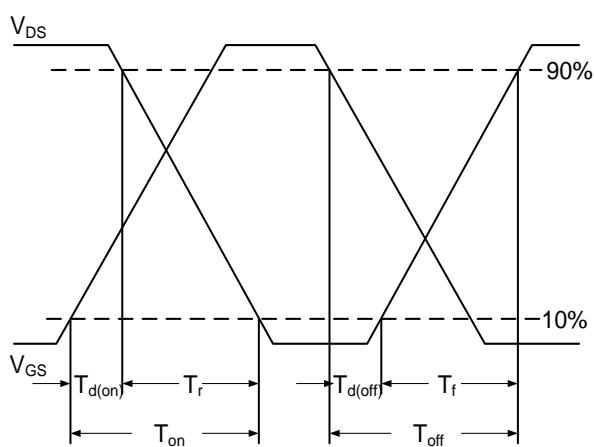
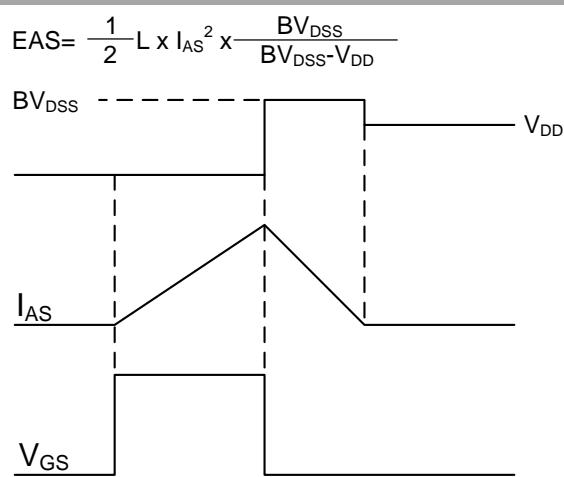


Fig.6 Normalized $R_{DS(on)}$ vs T_J


Fig.7 Capacitance

Fig.8 Safe Operating Area

Fig.9 Normalized Maximum Transient Thermal Impedance

Fig.10 Switching Time Waveform

Fig.11 Unclamped Inductive Switching Waveform